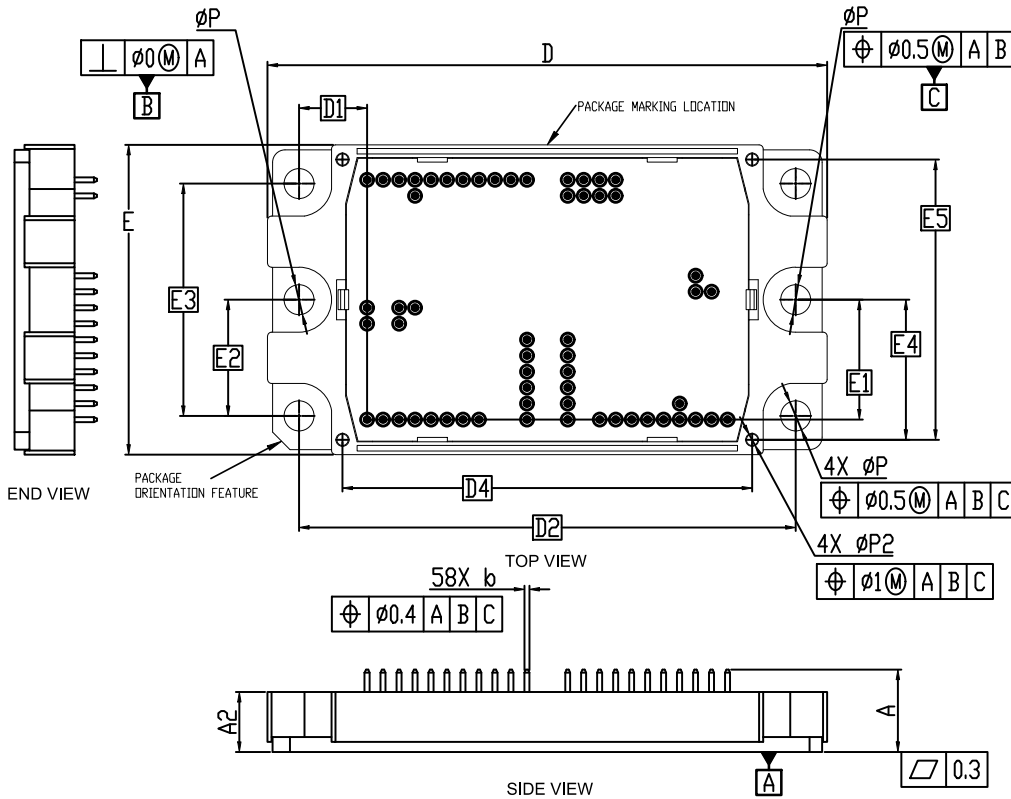


PIM58 112.00x62.00x12.00
CASE 180HX
ISSUE O

DATE 30 JUL 2024

NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5
2. All dimensions are in millimeters.
3. Pin-grid is 3.2mm.
4. Package marking is located on the side opposite the package orientation feature.
5. The pins are gold-plated solder pin.



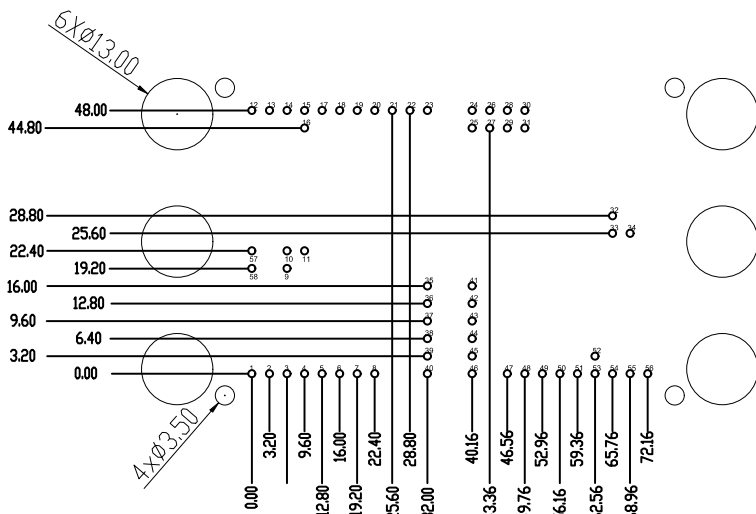
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	16.10	16.50	16.90
A2	11.70	12.00	12.30
b	0.95	1.00	1.05
D	111.60	112.00	112.40
D1	13.62 BSC		
D2	99.40 BSC		
D4	82.00 BSC		
E	61.60	62.00	62.40
E1	24.00 BSC		
E2	23.25 BSC		
E3	46.50 BSC		
E4	28.05 BSC		
E5	56.10 BSC		
P	5.90	6.00	6.10
P2	2.20	2.30	2.40

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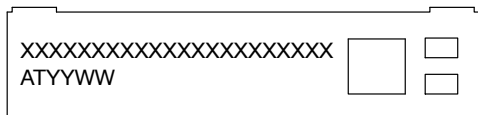
RECOMMENDED
MOUNTING PATTERN

* For additional Information on our Pb-Free strategy and soldering details, please download the Onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

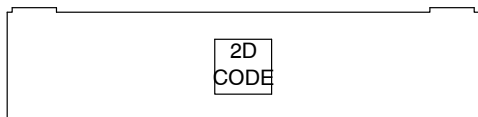
NOTE 2:

Pin table								
Pin	X	Y	Pin	X	Y	Pin	X	Y
1	0	0	24	40.16	48	47	46.56	0
2	3.2	0	25	40.16	44.8	48	49.76	0
3	6.4	0	26	43.36	48	49	52.96	0
4	9.6	0	27	43.36	44.8	50	56.16	0
5	12.8	0	28	46.56	48	51	59.36	0
6	16	0	29	46.56	44.8	52	62.56	3.2
7	19.2	0	30	49.76	48	53	62.56	0
8	22.4	0	31	49.76	44.8	54	65.76	0
9	6.4	19.2	32	65.76	28.8	55	68.96	0
10	6.4	22.4	33	65.76	25.6	56	72.16	0
11	9.6	22.4	34	68.96	25.6	57	0	22.4
12	0	48	35	32	16	58	0	19.2
13	3.2	48	36	32	12.8			
14	6.4	48	37	32	9.6			
15	9.6	48	38	32	6.4			
16	9.6	44.8	39	32	3.2			
17	12.8	48	40	32	0			
18	16	48	41	40.16	16			
19	19.2	48	42	40.16	12.8			
20	22.4	48	43	40.16	9.6			
21	25.6	48	44	40.16	6.4			
22	28.8	48	45	40.16	3.2			
23	32	48	46	40.16	0			

GENERIC
MARKING DIAGRAM*



FRONTSIDE MARKING



BACKSIDE MARKING

XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "µ", may or may not be present. Some products may not follow the Generic Marking.

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